TANDEM 64-TAP DIGITAL POTENTIOMETER

Check for Samples: TPL8002-25

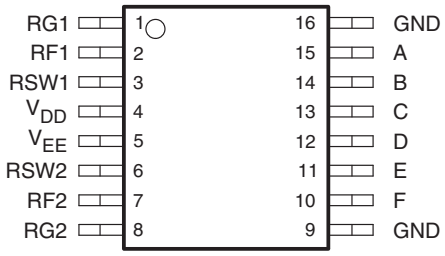
FEATURES

- **Adjustable Gain From 23.25 dB to –24 dB**
- **64-Tap Positions With 0.75 dB Per Step**
- **Supports 8-MHz Analog Bandwidth**
- **Operating Range up to –4-V V_{EE}/+4-V V_{DD}**
- **100-µA Maximum Static Supply Current**
- **±30% End-to-End Resistance Tolerance**
- **Absolute Tolerance of ±0.3 dB**
- **Operating Temperature Range From –40°C to 85°C**
- **ESD Performance Tested Per JESD 22**
  - **2000-V Human-Body Model (A114-B,Class II)**

APPLICATIONS

- **Tandem Adjustable Feedback and Gain Resistors for Operational Amplifers**

PW PACKAGE
(TOP VIEW)



DESCRIPTION/ORDERING INFORMATION

The TPL8002-25 is a programmable resistor device implementing two digital potentiometers with 64 wiper positions each that are tandem controlled through a 6-bit parallel interface. The device has fixed wiper resistances at the respective wiper contacts that tap the potentiometer resistors at a point determined by the binary code present at its digital inputs.

The resistive wiper tap terminals, RSW, of the TPL8002-25 are typically connected to the inverting inputs (–) of an external differential path inverting operational amplifier configuration, with the non-inverting inputs (+) connected through to ground. The application's differential input to the configuration is the device's RG terminals. The differential output of the external operational amplifiers is connected to the device's RF terminals, and thus becomes the differential output of the application configuration.

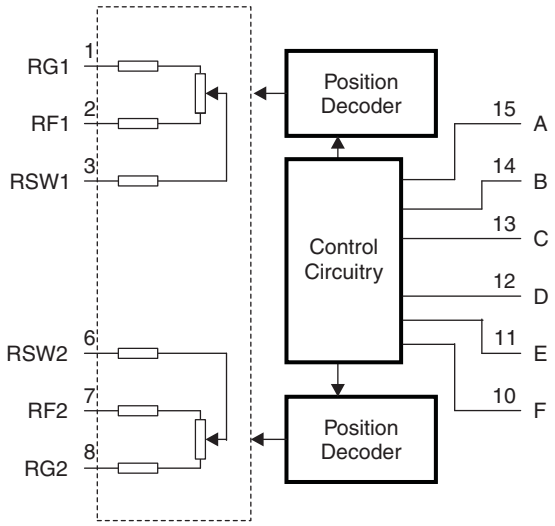
The resistance between the wiper contacts and the end points RG and RF of the TPL8002-25 provides a logarithmic gain/attenuation response of the configuration. With a digital code of decimal 0 (b000000) the configuration has an inverting maximum attenuation of –24 dB. With a digital code of decimal 32 (b100000) the configuration has inverting unity gain of 0.00 dB. With a digital code of decimal 63 (b111111) the configuration has an inverting maximum gain of +23.25 dB. The response of the configuration with respect to the digital code varies in fixed steps of 0.75 dB.

ORDERING INFORMATION

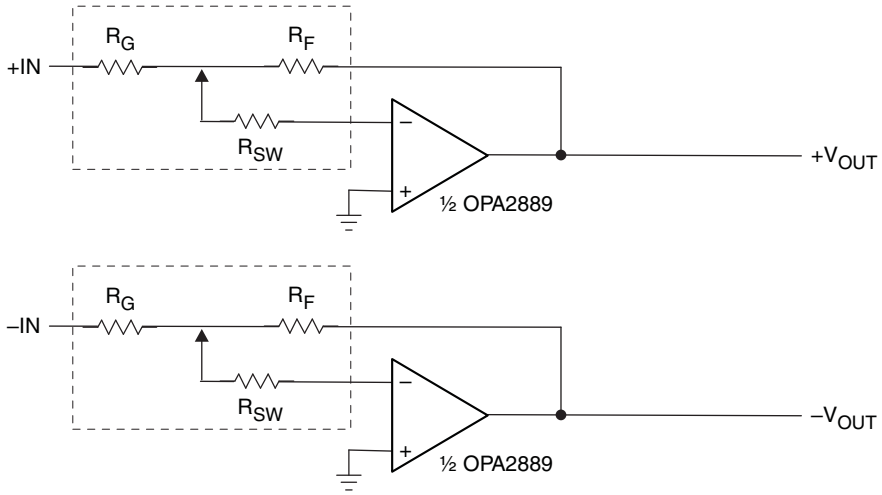
T_A	PACKAGE(1) (2)		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 85°C	TSSOP – PW	Tape and reel	TPL8002-25PWR	PHY03A

(1) Package drawings, thermal data, and symbolization are available at www.ti.com/packaging.
(2) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI website at www.ti.com.

FUNCTIONAL BLOCK DIAGRAM



TYPICAL APPLICATION CIRCUIT



FUNCTION TABLE

Table 1. Switch Truth Table

DECIMAL CONTROL	FEDCBA	GAIN/ATTN (dB)	R_G (Ω)	R_F (Ω)
63	111111	23.25	161	2339
62	111110	22.5	174	2326
61	111101	21.75	189	2311
60	111100	21	205	2295
59	111011	20.25	221	2279
58	111010	19.5	239	2261
57	111001	18.75	259	2241
56	111000	18	280	2220
55	110111	17.25	302	2198
54	110110	16.5	325	2175
53	110101	15.75	351	2149
52	110100	15	377	2123
51	110011	14.25	406	2094
50	110010	13.5	436	2064
49	110001	12.75	468	2032
48	110000	12	502	1998
47	101111	11.25	537	1963
46	101110	10.5	575	1925
45	101101	9.75	614	1886
44	101100	9	655	1845
43	101011	8.25	697	1803
42	101010	7.5	742	1758
41	101001	6.75	787	1713
40	101000	6	835	1665
39	100111	5.25	883	1617
38	100110	4.5	933	1567
37	100101	3.75	984	1516
36	100100	3	1036	1464
35	100011	2.25	1089	1411
34	100010	1.5	1142	1358
33	100001	0.75	1196	1304
32	100000	0	1250	1250
31	011111	-0.75	1304	1196
30	011110	-1.5	1358	1142
29	011101	-2.25	1411	1089
28	011100	-3	1464	1036
27	011011	-3.75	1516	984
26	011010	-4.5	1567	933
25	011001	-5.25	1617	883
24	011000	-6	1665	835
23	010111	-6.75	1713	787
22	010110	-7.5	1758	742
21	010101	-8.25	1803	697
20	010100	-9	1845	655

Table 1. Switch Truth Table (continued)

DECIMAL CONTROL	FEDCBA	GAIN/ATTN (dB)	R_G (Ω)	R_F (Ω)
19	010011	-9.75	1886	614
18	010010	-10.5	1925	575
17	010001	-11.25	1963	537
16	010000	-12	1998	502
15	001111	-12.75	2032	468
14	001110	-13.5	2064	436
13	001101	-14.25	2094	406
12	001100	-15	2123	377
11	001011	-15.75	2149	351
10	001010	-16.5	2175	325
9	001001	-17.25	2198	302
8	001000	-18	2220	280
7	000111	-18.75	2241	259
6	000110	-19.5	2261	239
5	000101	-20.25	2279	221
4	000100	-21	2295	205
3	000011	-21.75	2311	189
2	000010	-22.5	2326	174
1	000001	-23.25	2339	161
0	000000	-24	2352	148

ABSOLUTE MAXIMUM RATINGS(1) (2)

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
$V_{DD} - V_{EE}$	Power supply delta voltage(3)			10	V
V_{DD}	Positive supply voltage range(3)		–0.3	5	V
V_{EE}	Negative supply voltage range(3)		0.3	–5	V
V_{IN}	Control input voltage range(2) (3)		–0.3	V_{DD} + 0.3	V
$V_{I/O}$	Resistor I/O voltage range(2) (3) (4)		V_{EE} – 0.3	V_{DD} + 0.3	V
I_{IK}	Control input clamp current	V_{IN} < 0 and $V_{I/O}$ < 0		–18	mA
$I_{I/OK}$	I/O port clamp current	V_{IN} < 0 and $V_{I/O}$ < 0		–18	mA
T_{stg}	Storage temperature range		–40	85	°C

(1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
(2) All voltages are with respect to ground, unless otherwise specified.
(3) The input and output voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
(4) V_I and V_O are used to denote specific conditions for $V_{I/O}$.

RECOMMENDED OPERATING CONDITIONS

over operating free-air temperature range (unless otherwise noted)

		MIN	TYP	MAX	UNIT
$V_{DD} - V_{EE}$	Power supply delta voltage			8	V
V_{DD}	Positive supply voltage	2.5	3.6	4	V
V_{EE}	Negative supply voltage	–2.5	–3.6	–4	V
V_{IH}	High-level control input voltage	V_{DD} × 0.65			V
V_{IL}	Low-level control input voltage			V_{DD} × 0.35	V
V_I	Control input voltage	GND		V_{DD}	V
$V_{I/O}$	Resistor inputs/outputs	V_{EE}		V_{DD}	V
T_A	Operating free-air temperature	–40		85	°C

ELECTRICAL CHARACTERISTICS
Dual ±4-V Supply

over operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
V_{IK}	Control inputs	V_{DD} = 4 V, I_{IN} = –18 mA			–1.8	V
I_{IN}		V_{DD} = 4 V, V_{IN} = V_{DD} or GND			±1	µA
I_{DD} + | I_{EE} |		V_{DD} = 4 V, V_{EE} = –4 V, V_{IN} = V_{DD} or GND, $I_{I/O}$ = 0			100	µA
C_{IN}	Control capacitance(1)	V_{DD} = 4 V, V_{IN} = V_{DD} or GND		3.2		pF
C_{RG}	RG capacitance(1)	V_{IN} = 0 V, frequency = 10 MHz		45		pF
C_{RF}	RF capacitance(1)	V_{IN} = 0 V, frequency = 10 MHz		45		pF
C_W	Wiper capacitance(1)	V_{IN} = 0 V, frequency = 10 MHz		45		pF
R	End-to-end resistance		1.75	2.5	3.25	kΩ
R_W	Wiper resistance				420	Ω
INL	Integral nonlinearity		–0.3		0.3	dB
DNL	Differential nonlinearity		–0.3		0.3	dB

(1) The AC method is a frequency domain measurement. A 10-MHz ac voltage signal of known dc offset and amplitude of 82.5 mV are applied to the pin under test. The imaginary component of the complex current is measured and used in the equation: $C = I_{im} / (2 \times \pi \times F \times V_{IN})$ where I_{im} = imaginary component of input current, V_{IN} = magnitude of input voltage, and F = frequency.

SWITCHING CHARACTERISTICS(1)

over operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{PS}	Contol to output step delay			100		ns
BW	Analog signal bandwidth	For a typical example, see Figure 2	8			MHz

(1) Typical bandwidth shown in Figure 2 supports 6 MHz minimum.

PARAMETER MEASUREMENT INFORMATION

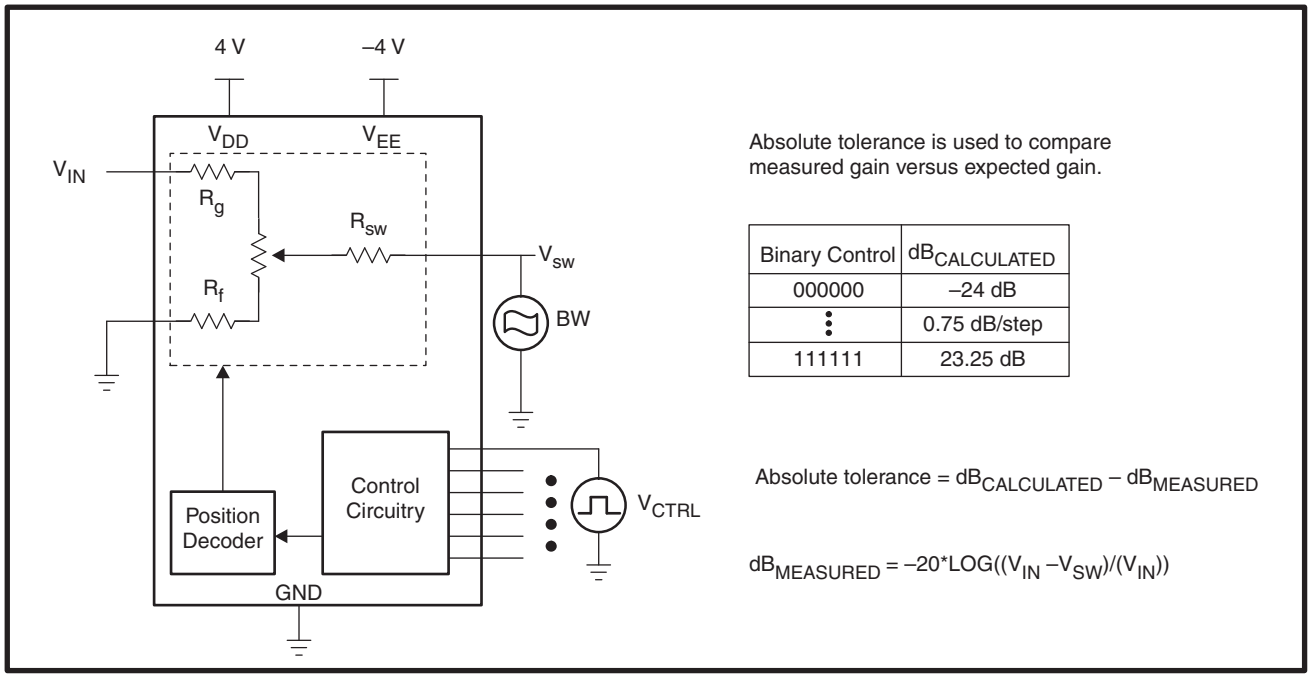


Figure 1. Analog Signal Bandwidth and Absolute Tolerance

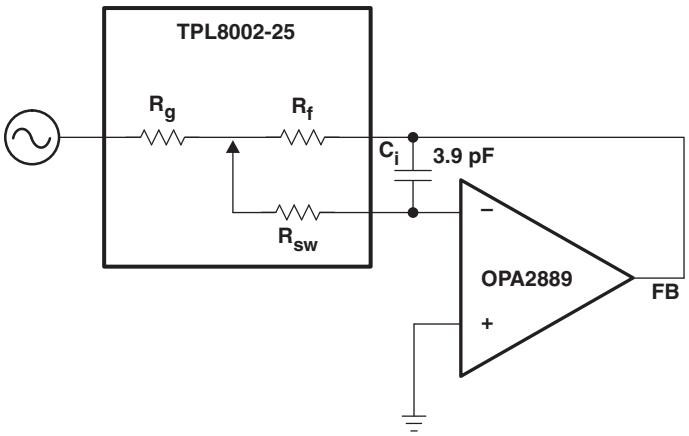


Figure 2. Bandwidth Setup

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
TPL8002-25PWR	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PHY03A	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

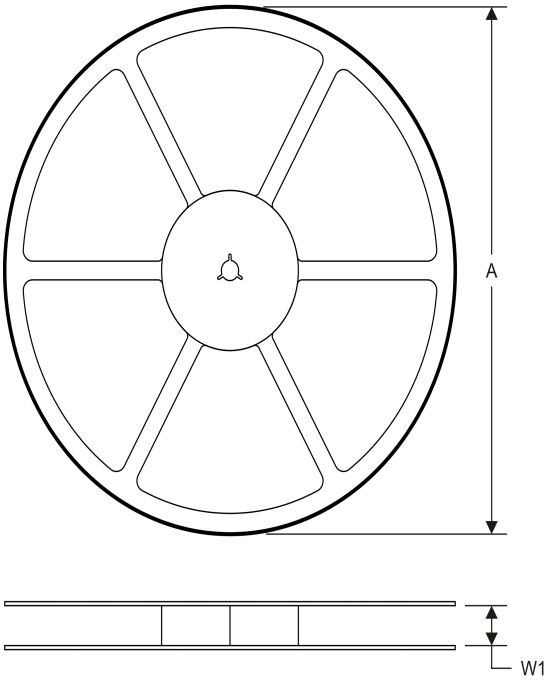
(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

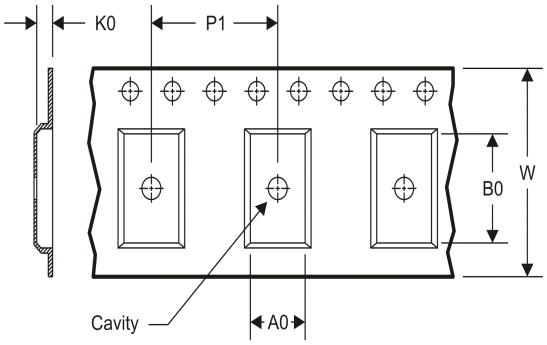
(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

TAPE AND REEL INFORMATION

REEL DIMENSIONS



TAPE DIMENSIONS



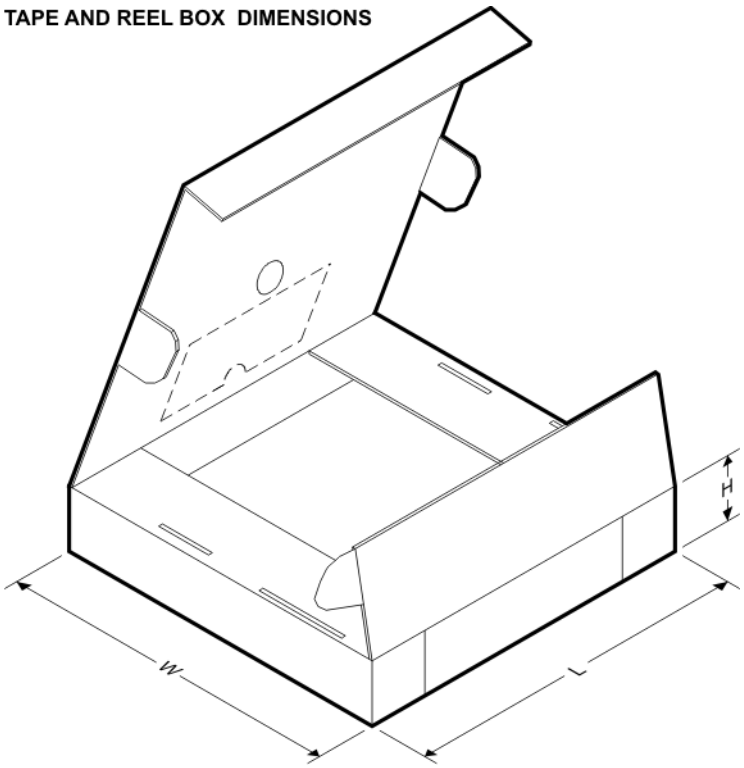
A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TPL8002-25PWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

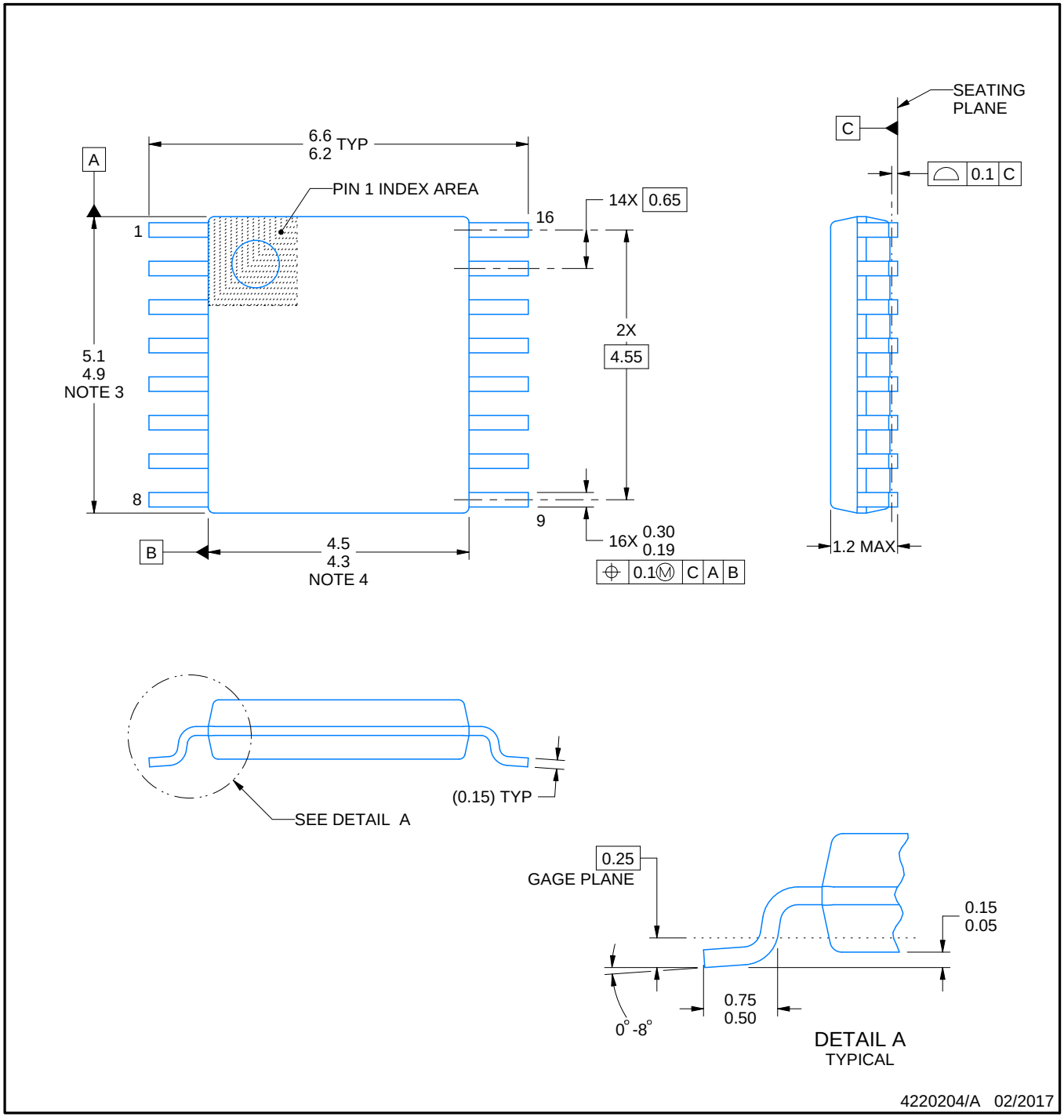
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TPL8002-25PWR	TSSOP	PW	16	2000	367.0	367.0	35.0

PACKAGE OUTLINE

PW0016A

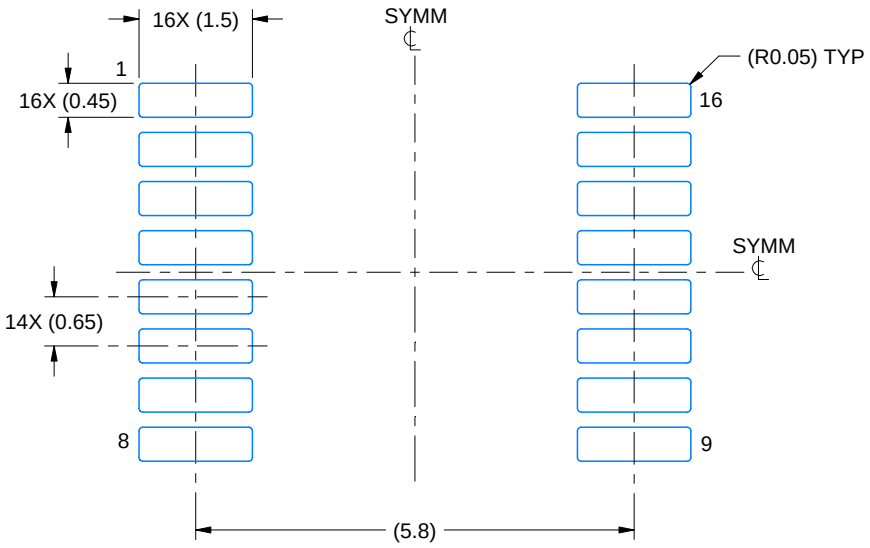
TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE

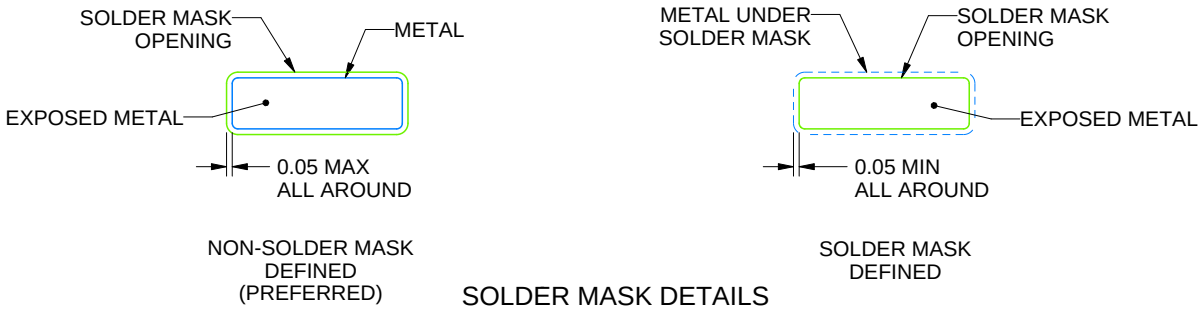


NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X



SOLDER MASK DETAILS

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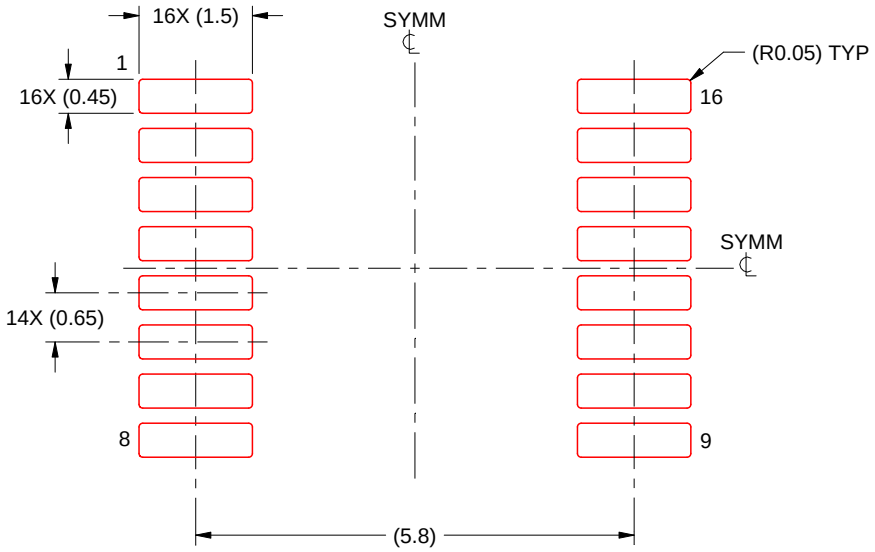
NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

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NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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